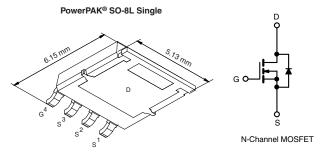


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Vishay Siliconix

# Automotive N-Channel 40 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0063			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0075			
I <sub>D</sub> (A)	58			
Configuration	Single			



#### **FEATURES**

- TrenchFET® Power MOSFET
- AEC-Q101 Qualified
- 100 % Rq and UIS Tested
- Material categorization:
   For definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ858AEP-T1-GE3

ABSOLUTE MAXIMUM RATINGS	$\bullet$ (1 <sub>C</sub> = 25 °C, unless	otnerwise noted	1)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	40	V	
Gate-Source Voltage		$V_{GS}$	± 20		
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	58		
Continuous Drain Current	T <sub>C</sub> = 125 °C	I <sub>D</sub>	33		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	43	Α	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	230		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	35		
Single Pulse Avalanche Energy	L = U. I IIII	E <sub>AS</sub>	61	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	D	48	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	16	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	00	
Soldering Recommendations (Peak Temperature)dd, e			260	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>b</sup>	$R_{thJA}$	85	°C/W
Junction-to-Case (Drain)		$R_{thJC}$	3.1	C/VV

#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. Parametric verification ongoing.
- d. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				ı	•		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		40		=-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	- V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125 °C	-		50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 175 °C	-	-	250	1
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 14 A	-	0.0050	0.0063	
Dunin Course On Chata Basistanas		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 10 A	-	0.0060	0.0075	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 14 A, T <sub>J</sub> = 125 °C	-	-	0.0120	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 14 A, T <sub>J</sub> = 175 °C	-	-	0.0150	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 14 V, I <sub>D</sub> = 16 A		-	99	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	1951	2450	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 20 V, f = 1 MHz	-	295	370	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	110	140	1
Total Gate Charge <sup>c</sup>	Qg			-	36	55	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 20 \text{ V}, I_{D} = 20 \text{ A}$	-	8	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		-	6	-	
Gate Resistance	R <sub>g</sub>		f = 1 MHz	1.5	2.97	4.5	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	10	15	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_{I} = 2 \Omega$		-	9	14	no
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>		$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	26	40	ns
Fall Time <sup>c</sup>	t <sub>f</sub>	1 1		-	8	12	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>	•			•		
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	230	Α
Forward Voltage	$V_{SD}$	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0		-	0.8	1.1	V

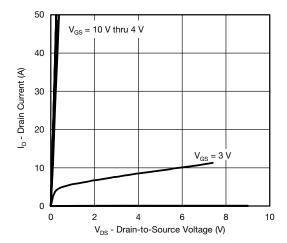
#### Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

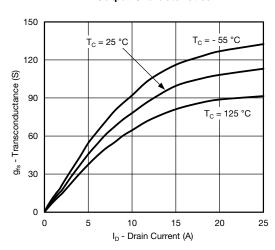
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



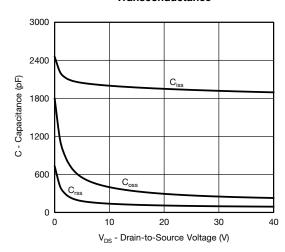
## TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



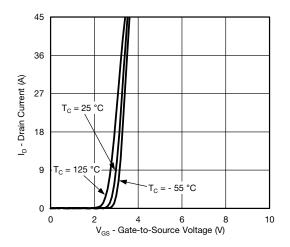
#### **Output Characteristics**



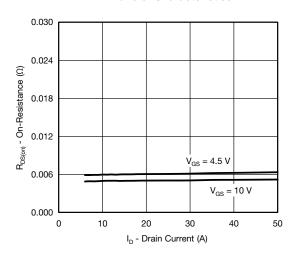
#### Transconductance



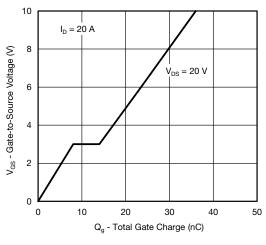
#### Capacitance



#### **Transfer Characteristics**



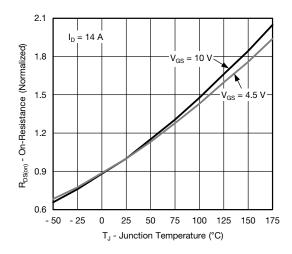
#### On-Resistance vs. Drain Current

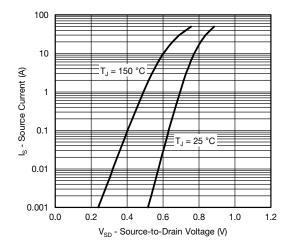


**Gate Charge** 

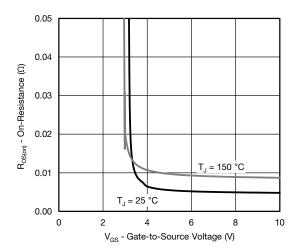


### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)

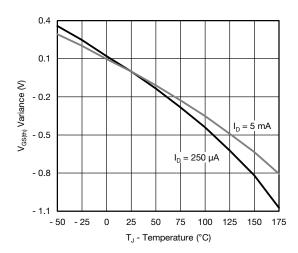




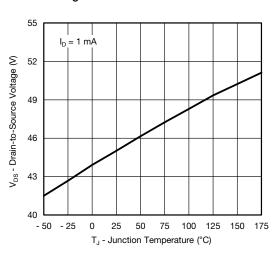
#### On-Resistance vs. Junction Temperature



**Source Drain Diode Forward Voltage** 



#### On-Resistance vs. Gate-to-Source Voltage

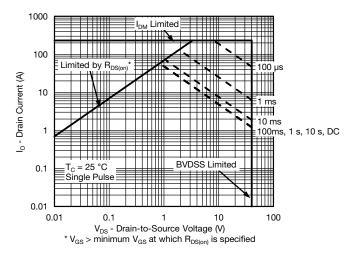


Threshold Voltage

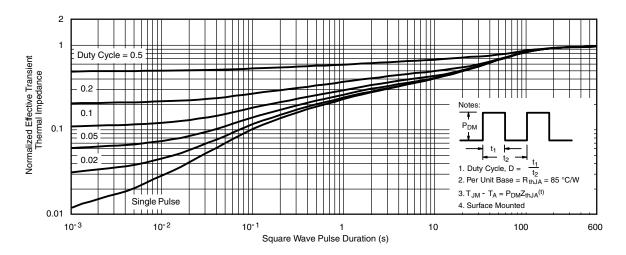
Drain Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)

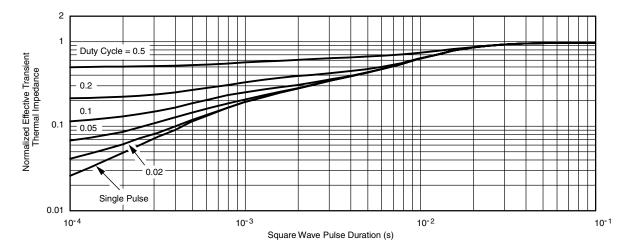


#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg263470">www.vishay.com/ppg263470</a>.



# PowerPAK® SO-8L Case Outline 2



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DIM.		MILLIMETERS			INCHES		
DIN.	MIN.	NOM.	NOM. MAX. MIN. NOM.			MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.05 6.15 6.25		0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23		0.009				
W1	0.41		0.016				
W2	2.82		0.111				
W3	2.96		0.117				
θ	0°	-	10°	0°	-	10°	

ECN: C21-1498-Rev. C, 01-Nov-2021

DWG: 6044

#### Note

• Millimeters will govern



#### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



## **Legal Disclaimer Notice**

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